

BSP317P-VB Datasheet

P-Channel 200V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (△)	I _D (A)	Q _g (Typ.)		
- 200	1.0 at V _{GS} = - 10 V	- 2.0	8.0		
	1.1 at V _{GS} = - 6.0 V	- 1.8	0.0		

FEATURES

 Halogen-free According to IEC 61249-2-21 Available

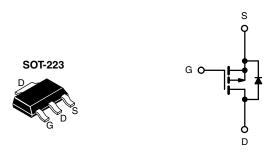


- · Ultra Low On-Resistance
- Small Size



APPLICATIONS

· Active Clamp Circuits in DC/DC Power Supplies



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 200		V	
Gate-Source Voltage		V _{GS}	± 20			
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 25 °C	I _D	- 2.0	- 1.68		
Continuous Drain Current (1 _J = 150 °C) ^{-5, 5}	T _A = 70 °C		- 1.8	- 1.56		
Pulsed Drain Current		I _{DM}	- 5.8		Α	
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6		
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.0			
Single Pulse Avalanche Energy	L = 1.011111	E _{AS}			mJ	
Marian and Danier Discipation 8 h	T _A = 25 °C	P _D	1.45	0.95	W	
Maximum Power Dissipation ^{a, b}	T _A = 70 °C		0.8	0.48	V V	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manifestore burnetten to Austrianta	t ≤ 5 s	R _{thJA}	75	100	°C/W
Maximum Junction-to-Ambient ^a	Steady State		120	166	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50	

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



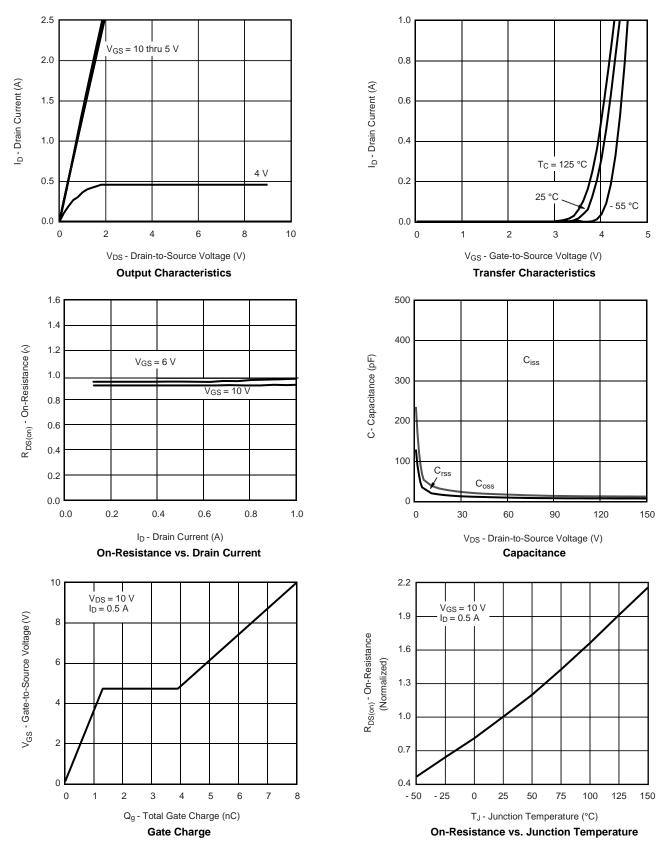
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 200			V	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2.5		- 4.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Brain Current		V _{DS} = - 200 V, V _{GS} = 0 V			- 1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 55 °C			- 10		
n-State Drain Current ^a		$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$ - 1.0			Α		
5		$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		0.80	1.00	^	
Drain-Source On-Resistance ^a	R _{DS(on)}	$V_{GS} = -6.0 \text{ V}, I_D = -0.5 \text{ A}$		0.90	1.10		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, I_D = -0.5 \text{ A}$		1.8		S	
Diode Forward Voltage	V _{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.85	- 1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	V 400 V V 40 V		8.0	12	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -100 \text{ V}, V_{GS} = 10 \text{ V}$ $I_{D} \approx -0.5 \text{ A}$		1.3			
Gate-Drain Charge	Q _{gd}	.b= 0.07.		2.5			
Gate Resistance	Rg	f = 1.0 MHz		8.0		^	
Input Capacitance	C _{iss}			370	510	pF	
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		28			
Reverse Transfer Capacitance	C _{rss}			16			
Switching ^c							
Turn-On Time	t _{d(on)}	V 100 V D 100		8	12	ns	
Tuni-On Time	t _r	$V_{DD} = -100 \text{ V}, R_L = 100 \land I_D \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$		11	17		
Turn-Off Time	t _{d(off)}	$R_a = 6 \wedge$		16	25	ns	
Tuiti-Oii Tiffle	t _f	y		11	17		
	Q _{rr}	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$		140	200	nC	

- a. Pulse test: PW \leq 300 μ s duty cycle \leq 2 %. b. For DESIGN AID ONLY, not subject to production testing. c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



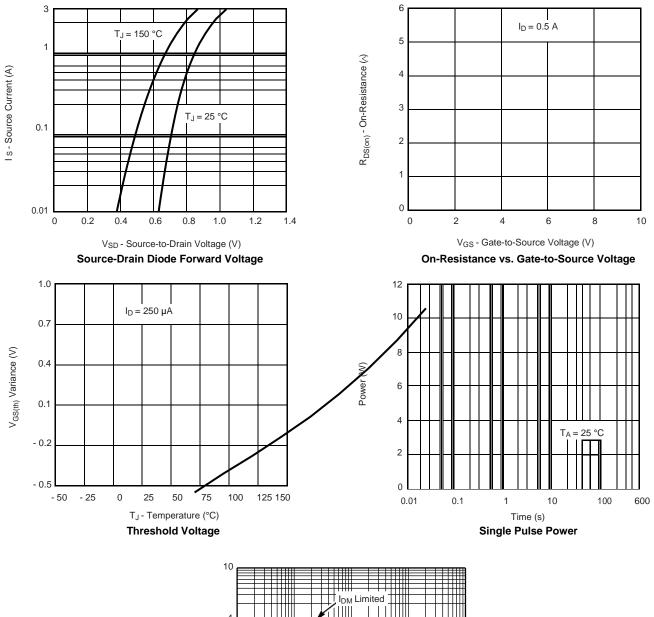
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

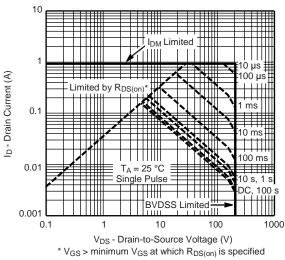






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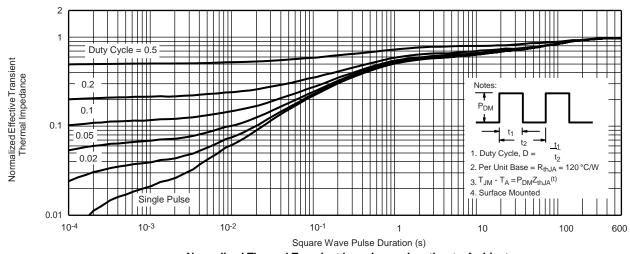




Safe Operating Area



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient





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